

# OSRAM KT CSLNM1.13

## Datasheet

Published by **ams-OSRAM AG**

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## OSRAM OSTAR® Projection Compact

# KT CSLNM1.13

Compact light source with isolated heat sink for improved heat dissipation and high current chip technology for increased light output.



### Applications

- Entertainment
- Factory Automation
- Projection & Display
- Visualization

### Features

- Package: white molded SMD ceramic package
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color:  $\lambda_{\text{dom}} = 525 \text{ nm}$  (● true green)
- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101-REV-C, Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

Ordering Information

| Type                 | Luminous Flux <sup>1)</sup><br>I <sub>F</sub> = 1000 mA<br>Φ <sub>V</sub> | Ordering Code |
|----------------------|---|---------------|
| KT CSLNM1.13-MXMZ-35 | 180 ... 280 lm  | Q65113A5079   |

## Maximum Ratings

| Parameter   | Symbol         |      | Values  |
|---|----------------|------|---------|
| Operating Temperature   | $T_{op}$       | min. | -40 °C  |
|   |                | max. | 125 °C  |
| Storage Temperature   | $T_{stg}$      | min. | -40 °C  |
|   |                | max. | 125 °C  |
| Junction Temperature  | $T_j$          | max. | 150 °C  |
| Forward current<br>$T_s = 25\text{ °C}$                                 | $I_F$          | min. | 40 mA   |
|   |                | max. | 3000 mA |
| Forward current pulsed<br>$D = 0.5$ ; $T_s = 25\text{ °C}$              | $I_{F\ pulse}$ | max. | 4000 mA |
| ESD withstand voltage<br>acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B) | $V_{ESD}$      |      | 8 kV    |
| Reverse current <sup>2)</sup>   | $I_R$          | max. | 200 mA  |

## Characteristics

 $I_F = 1000 \text{ mA}; T_S = 25 \text{ }^{\circ}\text{C}$ 

| Parameter   | Symbol                    |                      | Values                     |
|---|---------------------------|----------------------|----------------------------|
| Peak Wavelength   | $\lambda_{\text{peak}}$   | typ.                 | 521 nm                     |
| Dominant Wavelength <sup>3)</sup><br>$I_F = 1000 \text{ mA}; T_S = 25 \text{ }^{\circ}\text{C}$               | $\lambda_{\text{dom}}$    | min.<br>typ.<br>max. | 519 nm<br>525 nm<br>537 nm |
| Viewing angle at 50% $I_V$  | $2\phi$                   | typ.                 | 120 °                      |
| Radiating surface   | $A_{\text{color}}$        | typ.                 | 1 x 1 mm <sup>2</sup>      |
| Partial Flux acc. CIE 127:2007  | $\Phi_{E/V, 120^{\circ}}$ | typ.                 | 0.76                       |
| Forward Voltage <sup>4)</sup><br>$I_F = 1000 \text{ mA}$  | $V_F$                     | min.<br>typ.<br>max. | 2.3 V<br>2.9 V<br>3.3 V    |
| Reverse voltage (ESD device)  | $V_{R \text{ ESD}}$       | min.                 | 45 V                       |
| Reverse voltage <sup>2)</sup><br>$I_R = 20 \text{ mA}$  | $V_R$                     | max.                 | 1.2 V                      |
| Real thermal resistance junction/solderpoint <sup>5)</sup>  | $R_{\text{thJS real}}$    | typ.<br>max.         | 4.1 K / W<br>4.9 K / W     |
| Electrical thermal resistance junction/solderpoint <sup>5)</sup><br>with efficiency $\eta_e = 11 \text{ } \%$ | $R_{\text{thJS elec.}}$   | typ.<br>max.         | 3.6 K / W<br>4.4 K / W     |

## Brightness Groups

| Group | Luminous Flux <sup>1)</sup><br>$I_F = 1000 \text{ mA}$<br>min.<br>$\Phi_V$ | Luminous Flux <sup>1)</sup><br>$I_F = 1000 \text{ mA}$<br>max.<br>$\Phi_V$ |
|-------|--|--|
| MX    | 180 lm   | 210 lm   |
| MY    | 210 lm   | 240 lm   |
| MZ    | 240 lm   | 280 lm   |

## Wavelength Groups

| Group | Dominant Wavelength <sup>3)</sup><br>$I_F = 1000 \text{ mA}$<br>min.<br>$\lambda_{\text{dom}}$ | Dominant Wavelength <sup>3)</sup><br>$I_F = 1000 \text{ mA}$<br>max.<br>$\lambda_{\text{dom}}$ |
|-------|--|--|
| 3     | 519 nm   | 525 nm   |
| 4     | 525 nm   | 531 nm   |
| 5     | 531 nm   | 537 nm   |

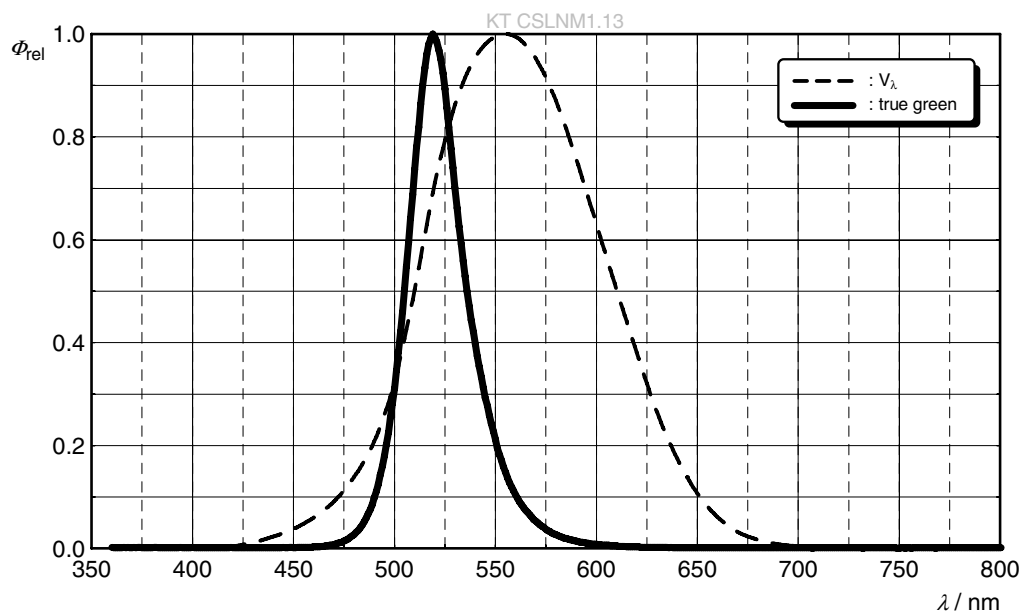
## Group Name on Label

### Example: MX-3

| Brightness | Wavelength |
|------------|------------|
| MX         | 3          |

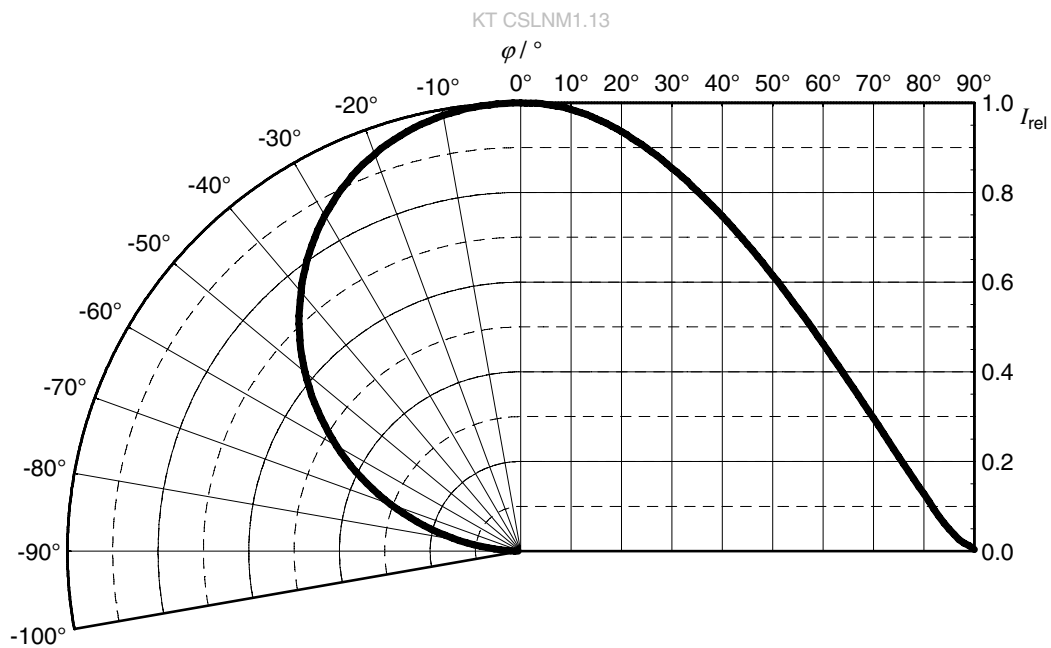
## Relative Spectral Emission <sup>6)</sup>

$\Phi_{\text{rel}} = f(\lambda)$ ;  $I_F = 1000 \text{ mA}$ ;  $T_J = 25 \text{ }^\circ\text{C}$



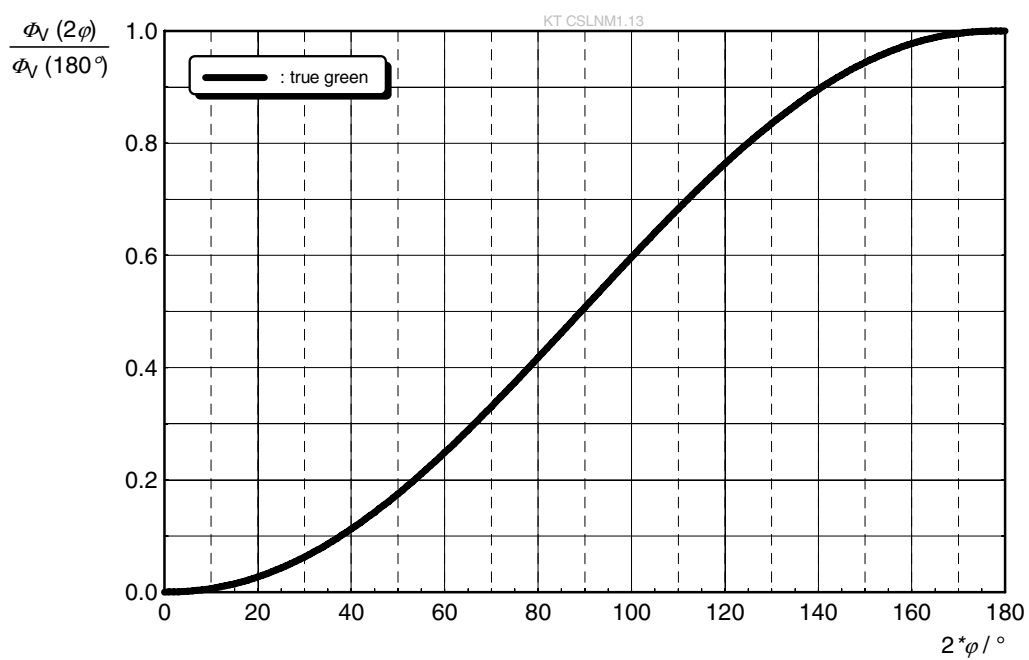
## Radiation Characteristics <sup>6)</sup>

$I_{\text{rel}} = f(\phi)$ ;  $T_J = 25 \text{ }^\circ\text{C}$



## Relative Partial Flux <sup>6)</sup>

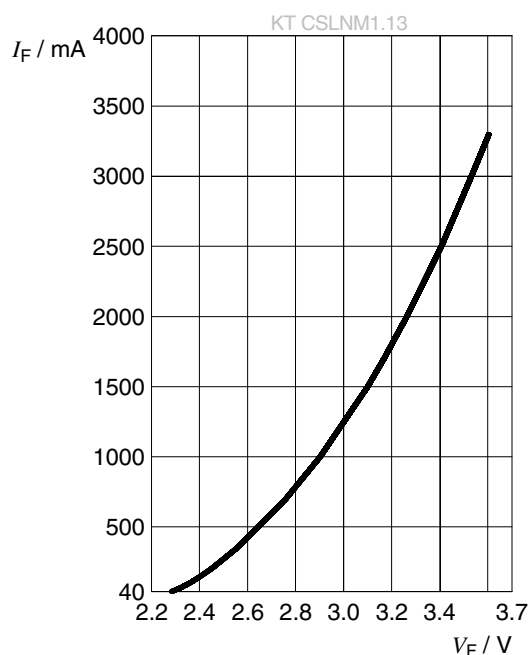
$\Phi_V(2\varphi)/\Phi_V(180^\circ) = f(\varphi); T_J = 25^\circ\text{C}$





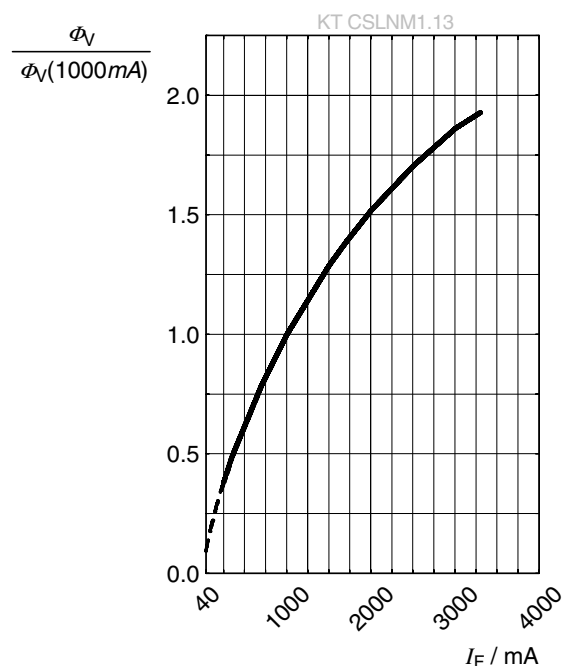
## Forward current <sup>6)</sup>

$$I_F = f(V_F); T_J = 25\text{ °C}$$



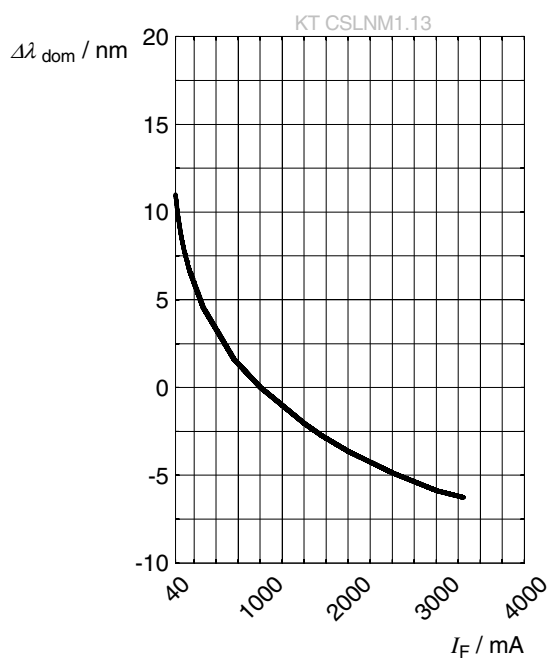
## Relative Luminous Flux <sup>6), 7)</sup>

$$\Phi_V / \Phi_V(1000\text{ mA}) = f(I_F); T_J = 25\text{ °C}$$



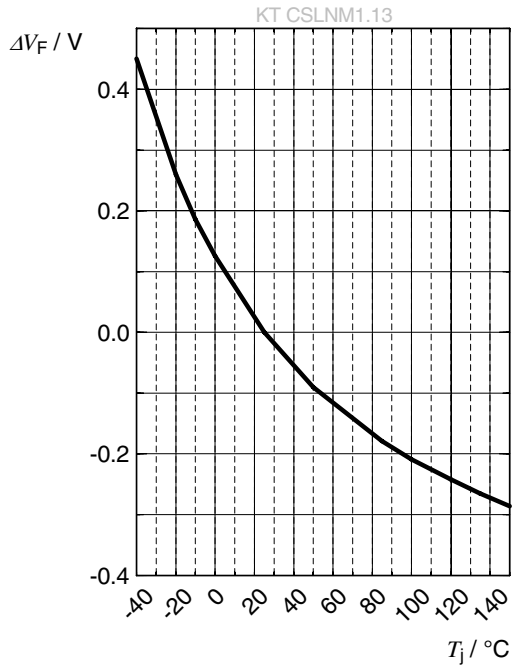
## Dominant Wavelength <sup>6)</sup>

$$\Delta\lambda_{\text{dom}} = f(I_F); T_J = 25\text{ °C}$$



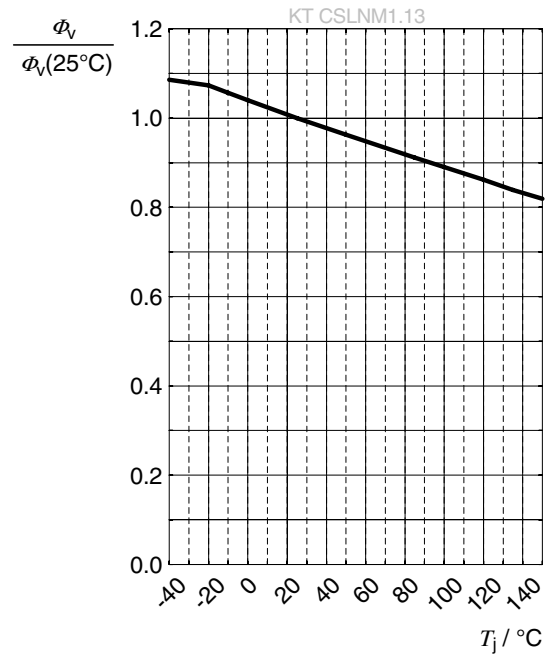
## Forward Voltage <sup>6)</sup>

$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 1000 \text{ mA}$$



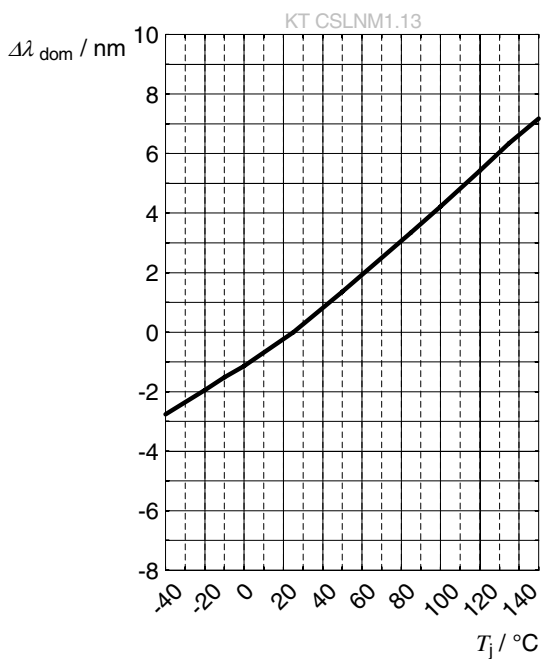
## Relative Luminous Flux <sup>6)</sup>

$$\Phi_V / \Phi_V(25^\circ\text{C}) = f(T_j); I_F = 1000 \text{ mA}$$



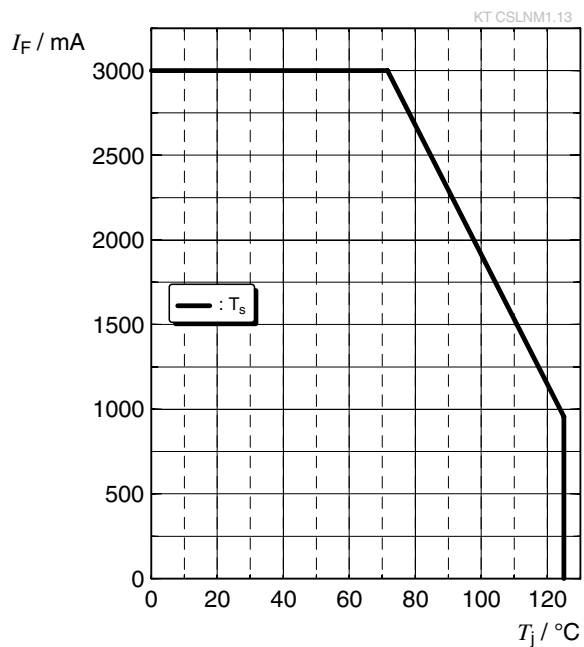
## Dominant Wavelength <sup>6)</sup>

$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}}(25^\circ\text{C}) = f(T_j); I_F = 1000 \text{ mA}$$



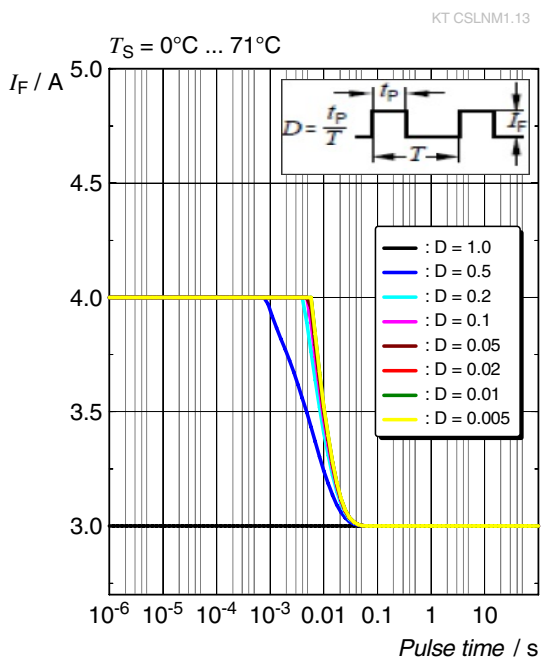
## Max. Permissible Forward Current

$$I_F = f(T)$$



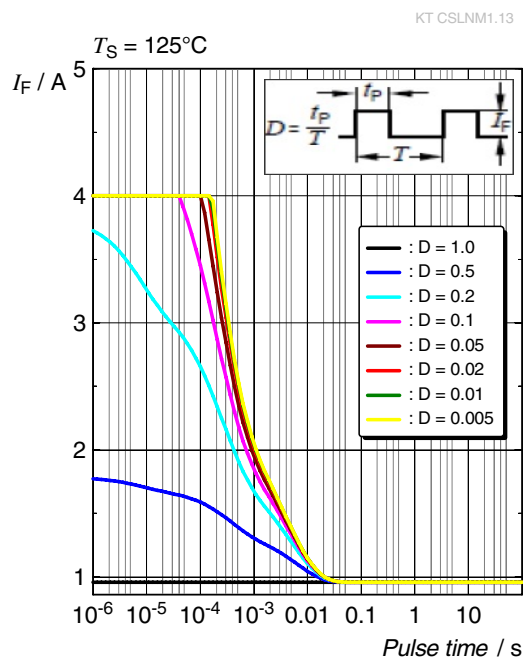
## Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}$$



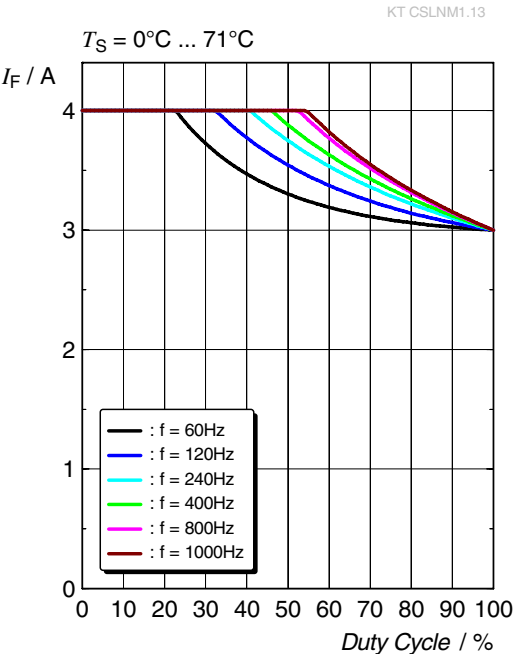
## Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}$$



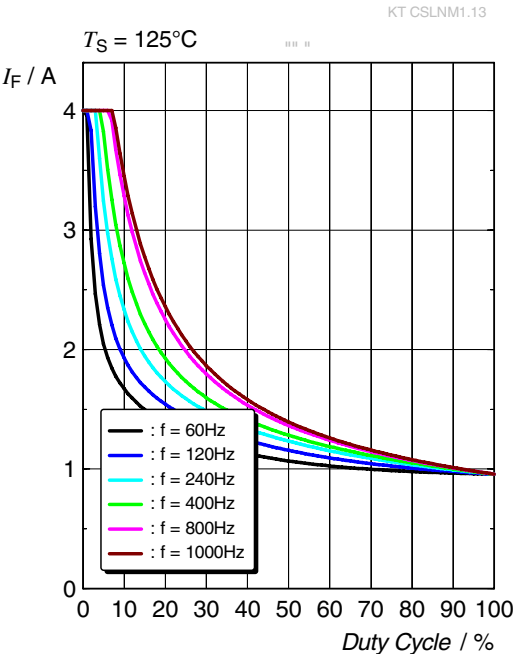
Permissible F. Handling Capability

f: Frequency

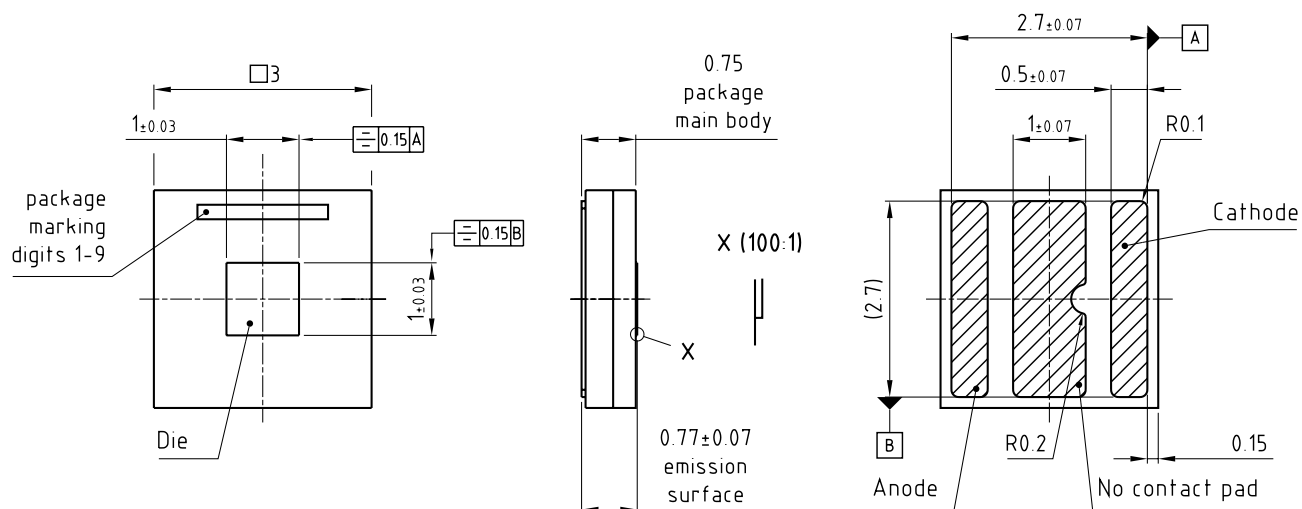


Permissible F. Handling Capability

f: Frequency



## Dimensional Drawing <sup>8)</sup>



general tolerance  $\pm 0.1$

lead finish Au 

C63062-A4312-A3 -04

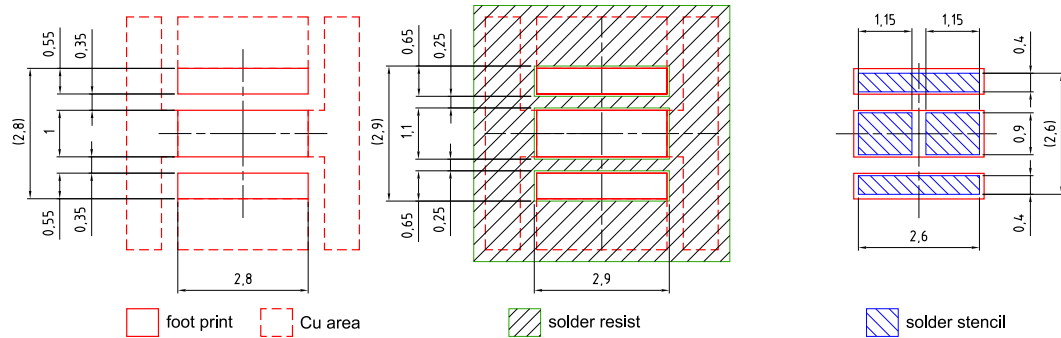
## Further Information:

**Approximate Weight:** 34.0 mg

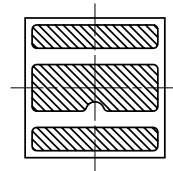
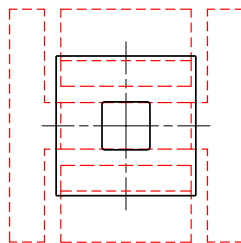
**Package marking:** Cathode

**ESD advice:** The device is protected by ESD device which is connected in parallel to the Chip.

## Recommended Solder Pad <sup>8)</sup>



Component Location on Pad

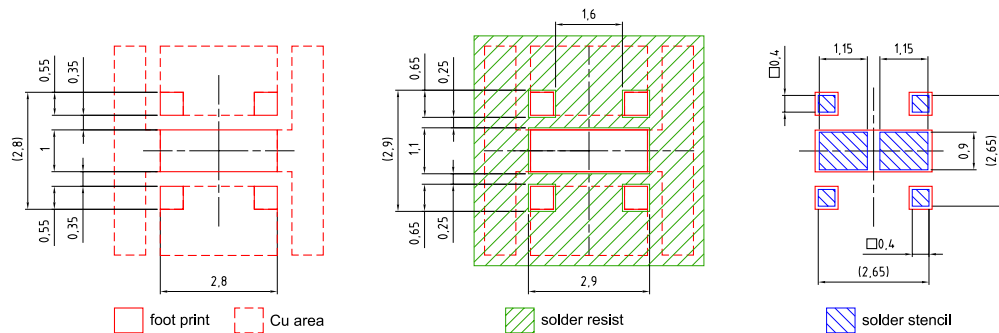


board material selection has high impact on system reliability

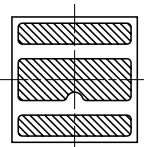
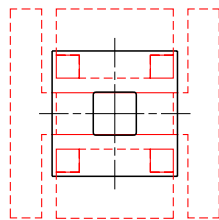
E062.3010.208 -02

## Recommended Solder Pad <sup>8)</sup>

Alternative Solder pad design for pedestal MCPCB



Component Location on Pad



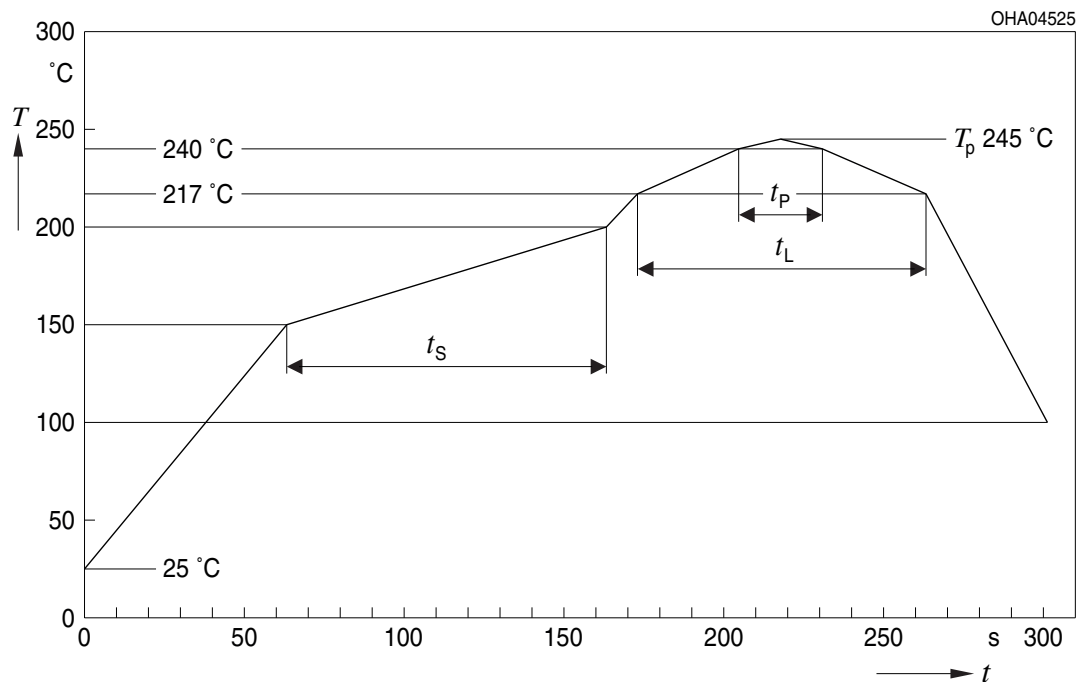
board material selection has high impact on system reliability

E062.3010.237-01

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for any kind of wet cleaning or ultrasonic cleaning.

## Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

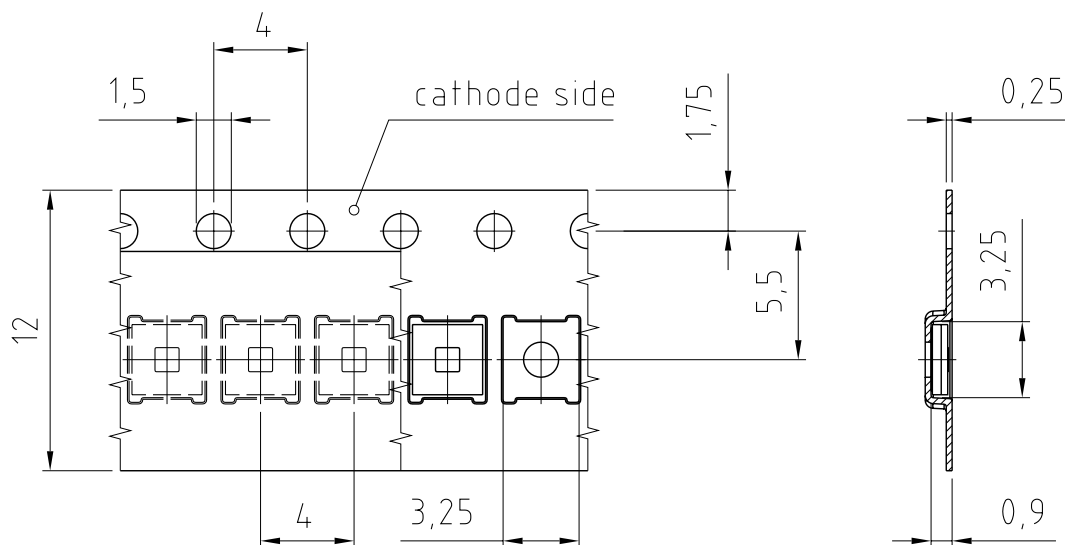


| Profile Feature  | Symbol | Pb-Free (SnAgCu) Assembly |                |         | Unit               |
|--|--------|---------------------------|----------------|---------|--------------------|
|  |        | Minimum                   | Recommendation | Maximum |                    |
| Ramp-up rate to preheat <sup>*)</sup><br>$25^{\circ}\text{C}$ to $150^{\circ}\text{C}$ |        |                           | 2              | 3       | K/s                |
| Time $t_s$<br>$T_{Smin}$ to $T_{Smax}$   | $t_s$  | 60                        | 100            | 120     | s                  |
| Ramp-up rate to peak <sup>*)</sup><br>$T_{Smax}$ to $T_p$                              |        |                           | 2              | 3       | K/s                |
| Liquidus temperature   | $T_L$  |                           | 217            |         | $^{\circ}\text{C}$ |
| Time above liquidus temperature  | $t_L$  |                           | 80             | 100     | s                  |
| Peak temperature   | $T_p$  |                           | 245            | 260     | $^{\circ}\text{C}$ |
| Time within $5^{\circ}\text{C}$ of the specified peak temperature $T_p - 5\text{ K}$   | $t_p$  | 10                        | 20             | 30      | s                  |
| Ramp-down rate <sup>*</sup><br>$T_p$ to $100^{\circ}\text{C}$                          |        |                           | 3              | 6       | K/s                |
| Time<br>$25^{\circ}\text{C}$ to $T_p$  |        |                           |                | 480     | s                  |

All temperatures refer to the center of the package, measured on the top of the component

<sup>\*</sup> slope calculation  $DT/Dt$ :  $Dt$  max. 5 s; fulfillment for the whole T-range

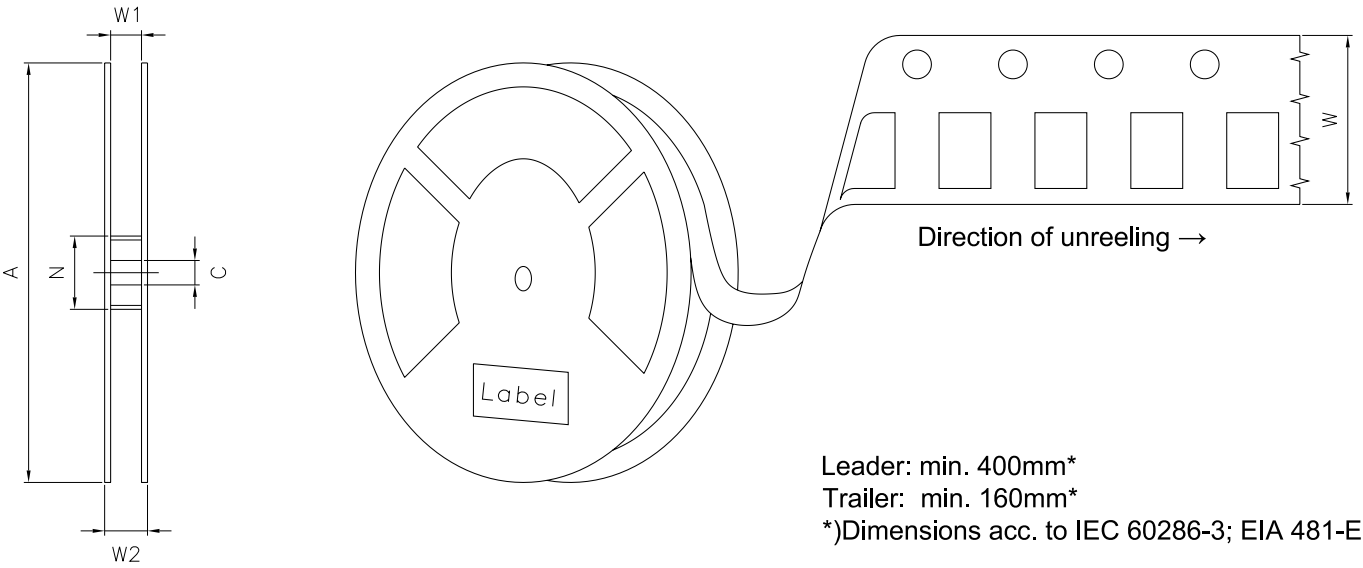
## Taping <sup>8)</sup>



C63062-A4312-B3-03



Tape and Reel <sup>9)</sup>



Reel Dimensions

| A      | W                   | N <sub>min</sub> | W <sub>1</sub> | W <sub>2max</sub> | Pieces per PU |
|--------|---------------------|------------------|----------------|-------------------|---------------|
| 180 mm | 12 + 0.3 / - 0.1 mm | 60 mm            | 12.4 + 2 mm    | 18.4 mm           |               |

## Barcode-Product-Label (BPL)

**OSRAM Opto Semiconductors**

LX XXXX
BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890

(1T) LOT NO: 1234567890

(9D) D/C: 1234

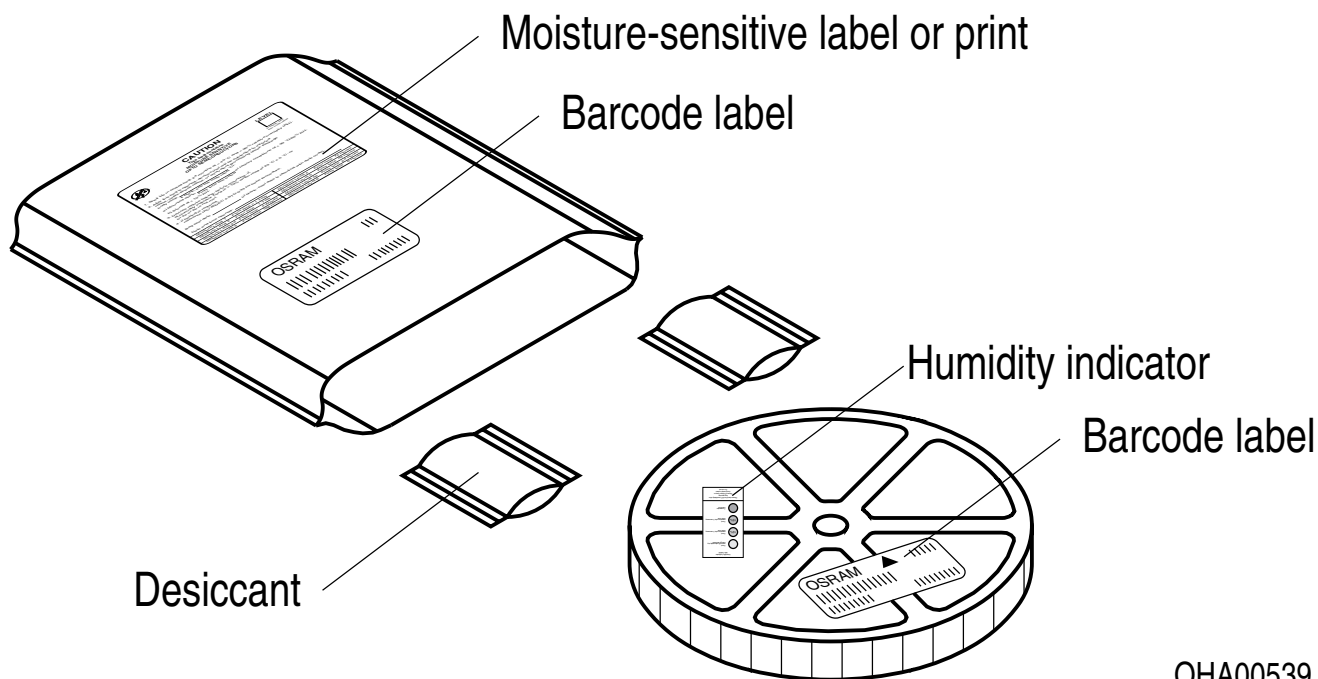
ML Temp ST  
X XXX °C X

Pack: RXX  
DEMY XXX  
X\_X123\_1234.1234 X

(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

OHA04563

## Dry Packing Process and Materials <sup>8)</sup>



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



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## Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit [www.osram-os.com/appnotes](http://www.osram-os.com/appnotes)

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## Disclaimer

### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

### Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

### Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

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## Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 8\%$  and an expanded uncertainty of  $\pm 11\%$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 2) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- 3) **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 0.5$  nm and an expanded uncertainty of  $\pm 1$  nm (acc. to GUM with a coverage factor of  $k = 3$ ).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of  $\pm 0.05$  V and an expanded uncertainty of  $\pm 0.1$  V (acc. to GUM with a coverage factor of  $k = 3$ ).
- 5) **Thermal Resistance:**  $R_{th\ max}$  is based on statistic values ( $6\sigma$ ).
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with  $\pm 0.1$  and dimensions are specified in mm.
- 9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

## Revision History

| Version | Date       | Change  |
|---------|------------|---|
| 1.0     | 2019-12-19 | Initial Version   |
| 1.1     | 2020-04-03 | Schematic Transportation Box<br>Dimensions of Transportation Box<br>Characteristics |
| 1.2     | 2022-08-11 | Characteristics<br>New Layout<br>Electro - Optical Characteristics (Diagrams)       |



EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；  
按照中国的相关法规和标准，  
不含有毒有害物质或元素。

**Published by ams-OSRAM AG**

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